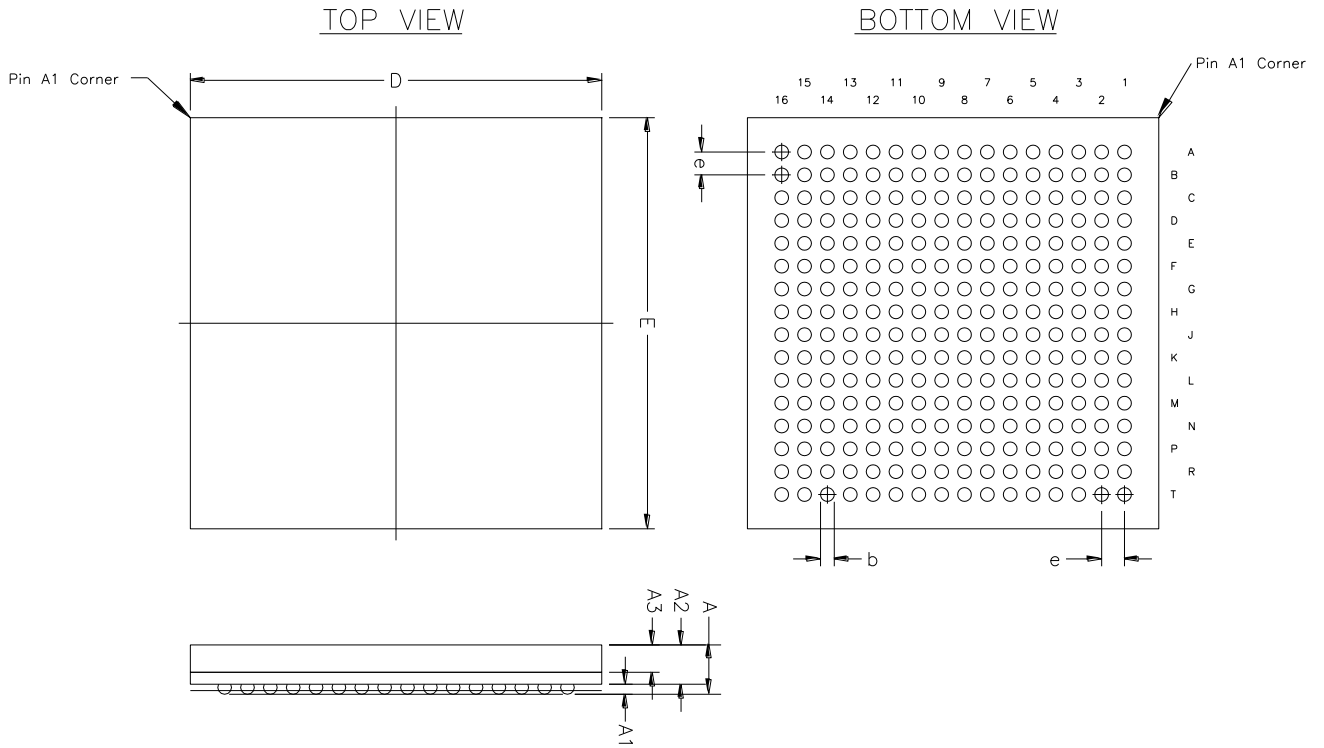


256-Pin Micro FineLine Ball-Grid Array (MBGA) - Wire Bond - A:1.20

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	Specification
Ordering Code Reference	M
Package Acronym	MBGA
Substrate Material	BT
Solder ball composition	Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MO-195 Variation: BF
Lead Coplanarity	0.003 inch (0.08 mm)
Weight	0.20 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	0.90	1.05	1.20
A1	0.17	0.22	0.27
A2	0.63	0.83	1.03
A3	0.55	0.60	0.65
D	9.00 BSC		
E	9.00 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		

Package Outline

Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
May 2012	1.0	Initial release



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